Form Type	Distribute	**Version**	2.0	**Ref**	IPC 1752A	**Sectionals**	Material Info	**Subsectionals**	D, A

Supplier Information

Company Name	TE Connectivity	**Request Document ID**		**Contact Name**	Benfer, David W	**Contact Title**	Prod Compliance Engineer, Eng Proc Opt/LEANPD
Company Unique ID	TE Connectivity	**Response Date**	2016-12-14	**Contact Email**	dave.benfer@te.com		
Contact Phone Number		717-986-3725					

Legal Statement

Supplier Acceptance	true

Legal Statement

The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.

Product

Manufacturer Item number	2041119-2	**Amount**	1170.7446	**Version**	-	**Identity**	
Manufacturer Item Name	mSATA/mini PCI-E 4H Type I 10u"	**Weight Uom**	mg	**Mfr Site**		**Authority**	
Date		**UOM**	Each				

EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products
EUREACH-1215	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed

Product Disclosure

Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	HOUSING				1.0	884.3	mg	
Substance	2	Carbon black	Supplier	1333-86-4	1.0	1.0	8.843	mg	
Substance	2	Talc (Mg3H2(SiO3)4)	Supplier	14807-96-6	10.0	1.0	88.43	mg	
Substance	2	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, [1,1-biphenyl]-4,4-diol and 4-hydroxybenzoic acid	Supplier	60088-52-0	69.0	1.0	610.167	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	20.0	1.0	176.86	mg	
Material	1	Gold Plating for UP CONTACT				1.0	0.0338	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0336986	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	1.014E-4	mg	
Material	1	LOW CONTACT				1.0	85.8	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.002574	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.085	1.0	0.07293	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	4.29E-4	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.0692406	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	80.78602	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	4.86186	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0069498	mg	
Material	1	Tin Plating for SOLDER PEGS				1.0	0.53	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	5.2947E-4	mg	
Substance	2	Tin	Supplier	7440-31-5	99.9001	1.0	0.52947	mg	

Material	1	SOLDER PEGS				1.0	22.6	mg	
Substance	2	Copper	Supplier	7440-50-8	64.23	1.0	14.51598	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0015	1.0	3.39E-4	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0082	1.0	0.0018532	mg	
Substance	2	Zinc	Supplier	7440-66-6	35.7546	1.0	8.08054	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0057	1.0	0.0012882	mg	
Material	1	UP CONTACT				1.0	171.6	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0807	1.0	0.13848	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.085	1.0	0.14586	mg	
Substance	2	Zinc	Supplier	7440-66-6	5.0E-4	1.0	8.58E-4	mg	
Substance	2	Iron	Supplier	7439-89-6	0.0081	1.0	0.0138996	mg	
Substance	2	Copper	Supplier	7440-50-8	94.1562	1.0	161.57204	mg	
Substance	2	Tin	Supplier	7440-31-5	5.6665	1.0	9.72371	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.005148	mg	
Material	1	Nickel Plating for UP CONTACT				1.0	3.614	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	3.59593	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.014456	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.003614	mg	
Material	1	Nickel Plating for SOLDER PEGS				1.0	0.27	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	0.26865	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	2.7E-4	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.00108	mg	
Material	1	Gold Plating for LOW CONTACT				1.0	0.0208	mg	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	0.0207376	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	6.24E-5	mg	
Material	1	Nickel Plating for LOW CONTACT				1.0	1.976	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.5	1.0	1.96612	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.4	1.0	0.007904	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.001976	mg	